

Revision History**512K x16 bit Super Low Power and Low Voltage Full CMOS Static RAM**

Revision No	History	Date	Remark
1.0	Initial Issue	August 2010	Preliminary
2.0	tDW updated to 25ns	October 2012	
3.0	Update USA HQ moved - change of address	September 2014	

FEATURES

- Process Technology : 0.15 μ m Full CMOS
- Organization : 512K x 16 bit
- Power Supply Voltage : 2.7V ~ 3.6V
- Low Data Retention Voltage : 1.5V(Min.)
- Three state output and TTL Compatible
- Package Type : 44pin TSOP2
- single CS – A6 is NC
- All parts are ROHS Compliant

GENERAL DESCRIPTION

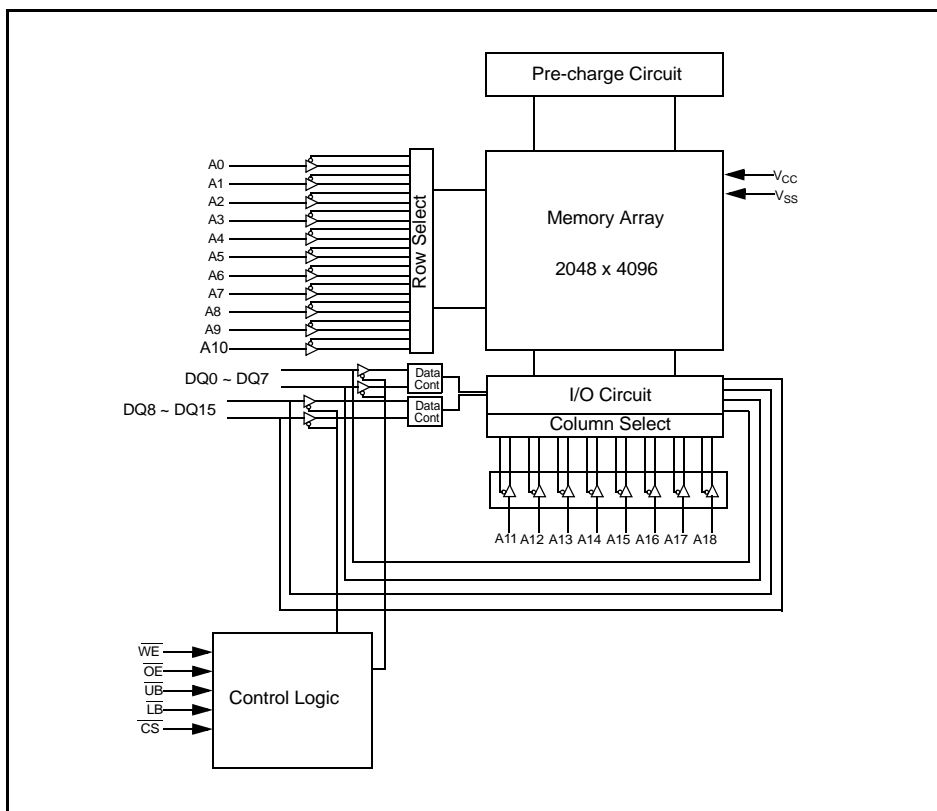
The AS6C8016A families are fabricated by advanced full CMOS process technology. The families support industrial temperature range and Chip Scale Package for user flexibility of system design. The families also support low data retention voltage for battery back- up operation with low data retention current.

PRODUCT FAMILY

Product Family	Operating Temperature	Vcc Range	Speed	Power Dissipation		PKG Type
				Standby (I _{SB1} , Typ.)	Operating (I _{CC1} -Max.)	
AS6C8016A-55ZIN	Industrial (-40 ~ 85°C)	2.7 ~ 3.6 V	55 ns	2 μ A ¹⁾	4 mA	44-TSOP2

Typical values are measured at Vcc=3.3V, T_A=25°C and not 100% tested.

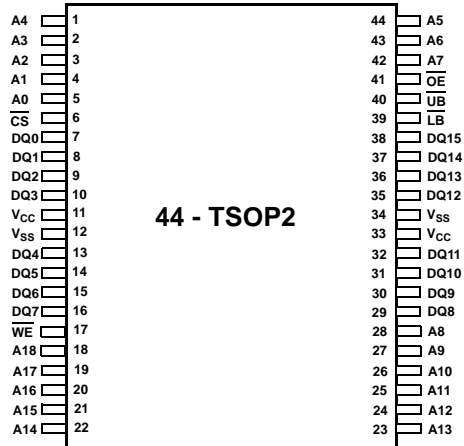
FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATIONS

44PIN TSOP2 : Top view- single CS – A6 is NC

44 - TSOP2 : Top view



PIN DESCRIPTION

Name	Function	Name	Function
$\overline{\text{CS}}$	Chip Select input	V_{CC}	Power Supply
$\overline{\text{OE}}$	Output Enable input	V_{SS}	Ground
$\overline{\text{WE}}$	Write Enable input	$\overline{\text{UB}}$	Upper Byte (DQ8~DQ15)
A0~A18	Address inputs	$\overline{\text{LB}}$	Lower Byte (DQ0~DQ7)
DQ0~DQ15	Data inputs/outputs	NC	No Connection

ABSOLUTE MAXIMUM RATINGS¹⁾

Parameter	Symbol	Ratings	Unit
Voltage on Any Pin Relative to V _{SS}	V _{IN} , V _{OUT}	-0.2 to 4.0	V
Voltage on V _{CC} supply relative to V _{SS}	V _{CC}	-0.2 to 4.0	V
Power Dissipation	P _D	1.0	W
Operating Temperature	T _A	-40 to 85	°C

1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation should be restricted to recommended operating condition. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

FUNCTIONAL DESCRIPTION

$\overline{\text{CS}}$	$\overline{\text{OE}}$	$\overline{\text{WE}}$	$\overline{\text{LB}}$	$\overline{\text{UB}}$	DQ0~7	DQ8~15	Mode	Power
H	X	X	X	X	High-Z	High-Z	Deselected	Stand by
X	X	X	H	H	High-Z	High-Z	Deselected	Stand by
L	H	H	L	X	High-Z	High-Z	Output Disabled	Active
L	H	H	X	L	High-Z	High-Z	Output Disabled	Active
L	L	H	L	H	Data Out	High-Z	Lower Byte Read	Active
L	L	H	H	L	High-Z	Data Out	Upper Byte Read	Active
L	L	H	L	L	Data Out	Data Out	Word Read	Active
L	X	L	L	H	Data In	High-Z	Lower Byte Write	Active
L	X	L	H	L	High-Z	Data In	Upper Byte Write	Active
L	X	L	L	L	Data In	Data In	Word Write	Active

NOTE : X means don't care. (Must be low or high state)

RECOMMENDED DC OPERATING CONDITIONS¹⁾

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	2.7	3.3	3.6	V
Ground	V_{SS}	0	0	0	V
Input high voltage	V_{IH}	2.2	-	$V_{CC} + 0.2$ ²⁾	V
Input low voltage	V_{IL}	-0.2 ³⁾	-	0.6	V

1. $T_A = -40$ to 85°C , otherwise specified
2. Overshoot: $V_{CC} + 2.0$ V in case of pulse width ≤ 20 ns
3. Undershoot: -2.0 V in case of pulse width ≤ 20 ns
4. Overshoot and undershoot are sampled, not 100% tested.

CAPACITANCE¹⁾ ($f = 1\text{MHz}$, $T_A = 25^\circ\text{C}$)

Item	Symbol	Test Condition	Min	Max	Unit
Input capacitance	C_{IN}	$V_{IN} = 0\text{V}$	-	8	pF
Input/Output capacitance	C_{IO}	$V_{IO} = 0\text{V}$	-	10	pF

1. Capacitance is sampled, not 100% tested

DC AND OPERATING CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input leakage current	I_{LI}	$V_{IN} = V_{SS}$ to V_{CC}	-1	-	1	μA
Output leakage current	I_{LO}	$\overline{CS} = V_{IH}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$ or $\overline{LB} = \overline{UB} = V_{IH}$ $V_{IO} = V_{SS}$ to V_{CC}	-1	-	1	μA
Operating power supply	I_{CC}	$I_{IO} = 0\text{mA}$, $\overline{CS} = V_{IL}$, $\overline{WE} = V_{IH}$, $V_{IN} = V_{IH}$ or V_{IL}	-	-	2	mA
Average operating current	I_{CC1}	Cycle time = $1\mu\text{s}$, 100% duty, $I_{IO} = 0\text{mA}$, $\overline{CS} < 0.2\text{V}$, $\overline{LB} < 0.2\text{V}$ or/and $\overline{UB} < 0.2\text{V}$, $V_{IN} < 0.2\text{V}$ or $V_{IN} > V_{CC} - 0.2\text{V}$	-	-	4	mA
	I_{CC2}	Cycle time = Min, $I_{IO} = 0\text{mA}$, 100% duty, $\overline{CS} = V_{IL}$, $\overline{LB} = V_{IL}$ or/and $\overline{UB} = V_{IL}$, $V_{IN} = V_{IL}$ or V_{IH}	55ns	-	35	mA
Output low voltage	V_{OL}	$I_{OL} = 2.1\text{mA}$	-	-	0.4	V
Output high voltage	V_{OH}	$I_{OH} = -1.0\text{mA}$	2.4	-	-	V
Standby Current (TTL)	I_{SB}	$\overline{CS} = V_{IH}$, Other inputs = V_{IH} or V_{IL}	-	-	0.5	mA
Standby Current (CMOS)	I_{SB1}	$\overline{CS} > V_{CC} - 0.2\text{V}$, Other inputs = $0 \sim V_{CC}$ (Typ. condition : $V_{CC} = 3.3\text{V}$ @ 25°C) (Max. condition : $V_{CC} = 3.6\text{V}$ @ 85°C)	LF	-	2 ¹⁾	15 μA

1. Typical values are measured at $V_{CC} = 3.3\text{V}$, $T_A = 25^\circ\text{C}$ and not 100% tested.

AC OPERATING CONDITIONS
Test Conditions (Test Load and Test Input/Output Reference)

Input Pulse Level: 0.4 to 2.4V

Input Rise and Fall Time: 5ns

Input and Output reference Voltage: 1.5V

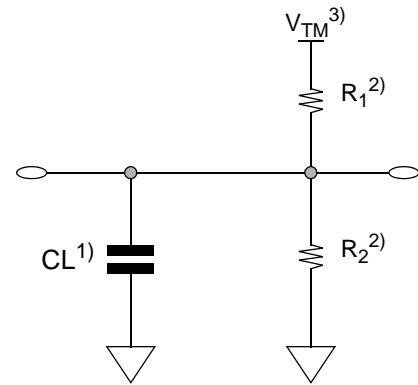
 Output Load (See right): $CL^{(1)} = 100\text{pF} + 1 \text{ TTL (70nsec)}$

$$CL^{(1)} = 30\text{pF} + 1 \text{ TTL (45ns/55ns)}$$

1. Including scope and Jig capacitance

 2. $R_1=3070\Omega$, $R_2=3150\Omega$

 3. $V_{TM}=2.8\text{V}$

 4. $CL = 5\text{pF} + 1 \text{ TTL (measurement with } t_{LZ}, t_{HZ}, t_{OLZ}, t_{OHZ}, t_{WHZ})$

READ CYCLE ($V_{CC} = 2.7$ to 3.6V , $Gnd = 0\text{V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

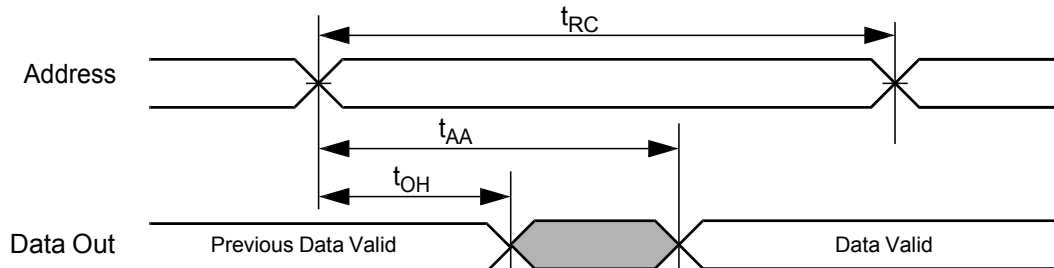
Parameter	Symbol	55ns		Unit
		Min	Max	
Read cycle time	t_{RC}	55	-	ns
Address access time	t_{AA}	-	55	ns
Chip select to output	t_{CO}	-	55	ns
Output enable to valid output	t_{OE}	-	35	ns
\overline{UB} , \overline{LB} access time	t_{BA}		55	ns
Chip select to low-Z output	t_{LZ}	5	-	ns
\overline{UB} , \overline{LB} enable to low-Z output	t_{BLZ}	5	-	ns
Output enable to low-Z output	t_{OLZ}	5	-	ns
Chip disable to high-Z output	t_{HZ}	0	20	ns
\overline{UB} , \overline{LB} disable to how-Z output	t_{BHZ}	0	20	ns
Output disable to high-Z output	t_{OHZ}	0	20	ns
Output hold from address change	t_{OH}	10	-	ns

WRITE CYCLE ($V_{CC} = 2.7$ to 3.6V , $Gnd = 0\text{V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

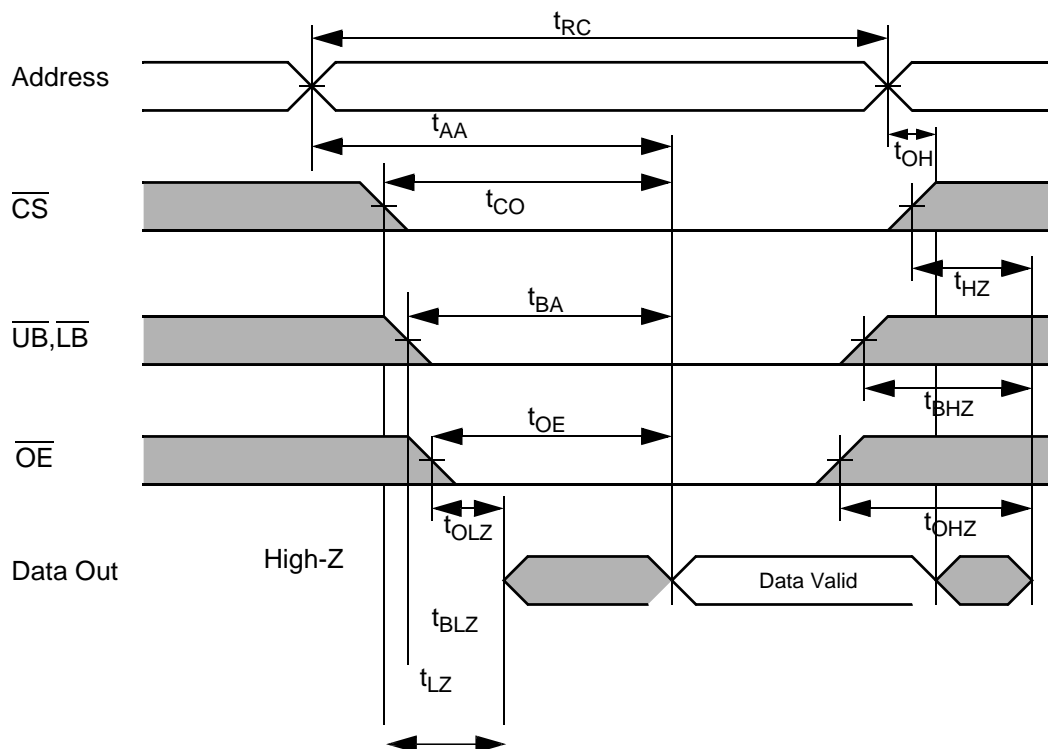
Parameter	Symbol	55ns		Unit
		Min	Max	
Write cycle time	t_{WC}	55	-	ns
Chip select to end of write	t_{CW}	45	-	ns
Address setup time	t_{As}	0	-	ns
Address valid to end of write	t_{AW}	45	-	ns
\overline{UB} , \overline{LB} valid to end of write	t_{BW}	45	-	ns
Write pulse width	t_{WP}	45	-	ns
Write recovery time	t_{WR}	0	-	ns
Write to output high-Z	t_{WHZ}	0	20	ns
Data to write time overlap	t_{DW}	25		ns
Data hold from write time	t_{DH}	0	-	ns
End write to output low-Z	t_{OW}	5		ns

TIMING DIAGRAMS

TIMING WAVEFORM OF READ CYCLE (1) (Address Controlled, $\overline{CS}=\overline{OE}=V_{IL}$, \overline{UB} or/and $\overline{LB}=V_{IL}$)

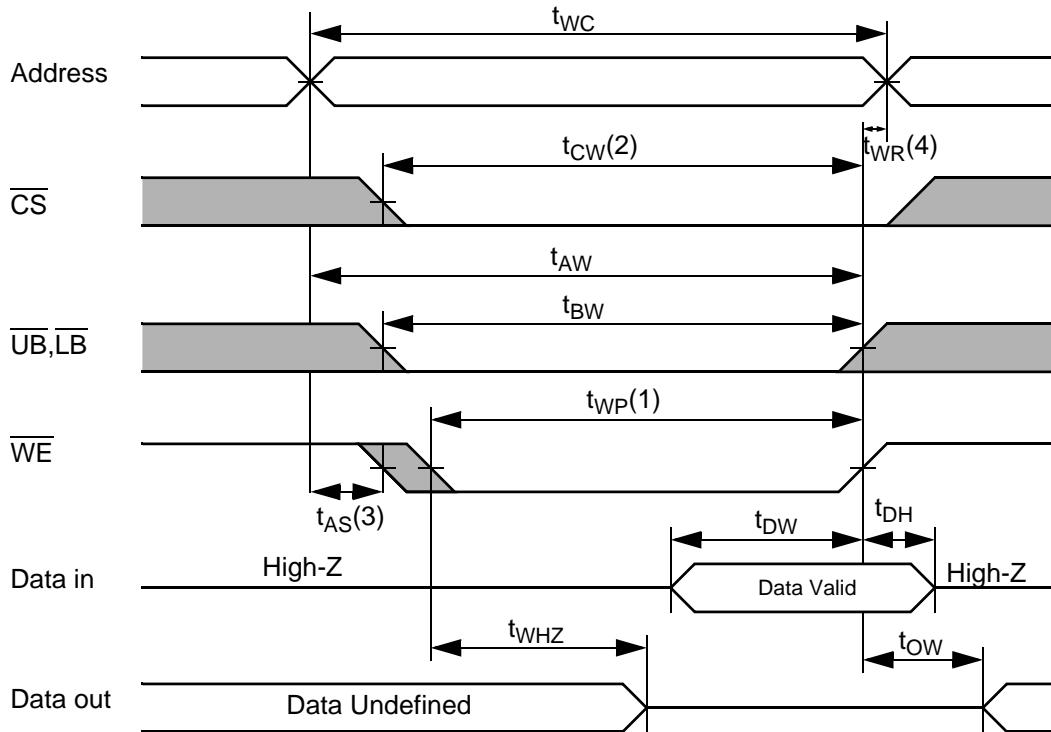
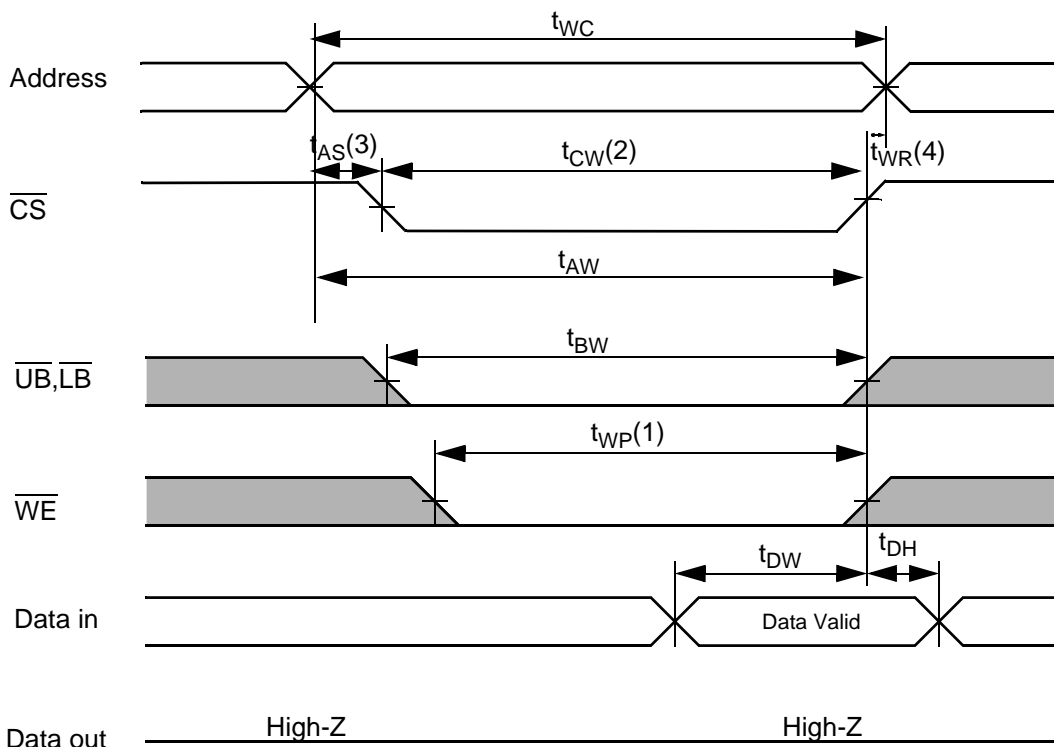


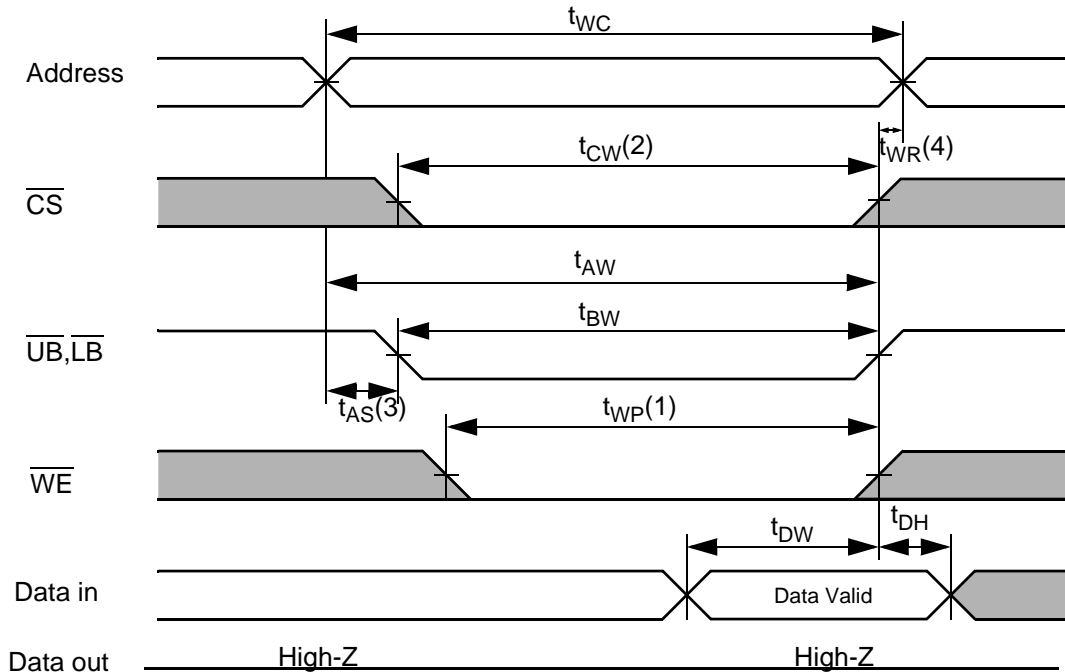
TIMING WAVEFORM OF READ CYCLE(2) ($\overline{WE} = V_{IH}$)



NOTES (READ CYCLE)

- t_{HZ} and t_{OHZ} are defined as the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
- At any given temperature and voltage condition, $t_{HZ}(\text{Max.})$ is less than $t_{LZ}(\text{Min.})$ both for a given device and from device to device interconnection.

TIMING WAVEFORM OF WRITE CYCLE(1) (\overline{WE} Controlled)

TIMING WAVEFORM OF WRITE CYCLE(2) (\overline{CS} Controlled)


TIMING WAVEFORM OF WRITE CYCLE(3) (\overline{UB} , \overline{LB} Controlled)

NOTES (WRITE CYCLE)

1. A write occurs during the overlap(t_{WP}) of low \overline{CS} and low \overline{WE} . A write begins when \overline{CS} goes low and \overline{WE} goes low with asserting \overline{UB} or \overline{LB} for single byte operation or simultaneously asserting \overline{UB} and \overline{LB} for double byte operation. A write ends at the earliest transition when \overline{CS} goes high and \overline{WE} goes high. The t_{WP} is measured from the beginning of write to the end of write.
2. t_{CW} is measured from the \overline{CS} going low to end of write.
3. t_{AS} is measured from the address valid to the beginning of write.
4. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as \overline{CS} or \overline{WE} going high.

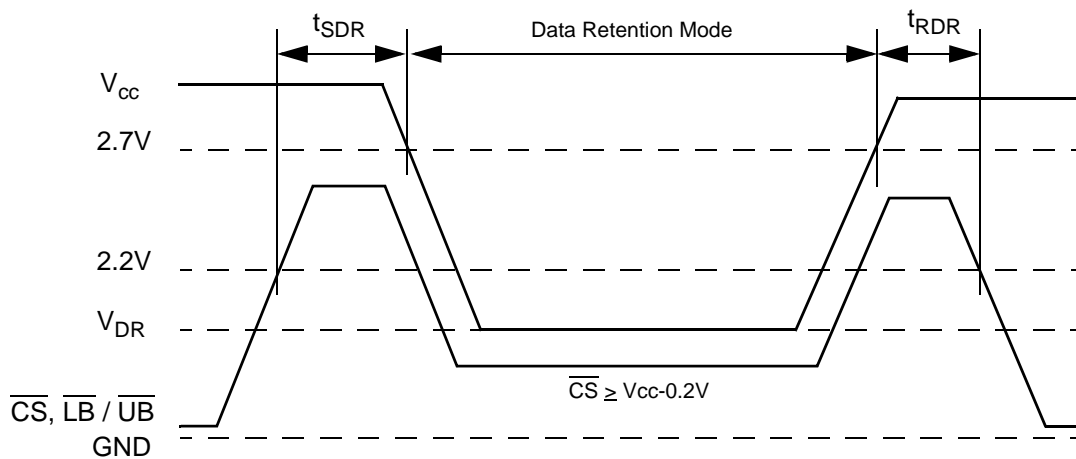
DATA RETENTION CHARACTERISTICS

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
V _{CC} for Data Retention	V _{DR}	I _{SB1} Test Condition (Chip Disabled) ¹	1.5	-	3.6	V
Data Retention Current	I _{DR}	V _{CC} =1.5V, I _{SB1} Test Condition (Chip Disabled) ¹	-	-	4	μA
Chip Deselect to Data Retention Time	t _{SDR}	See data retention wave form	0	-	-	ns
Operation Recovery Time	t _{RDR}		t _{RC}	-	-	

NOTES

1. See the I_{SB1} measurement condition of datasheet page 5.

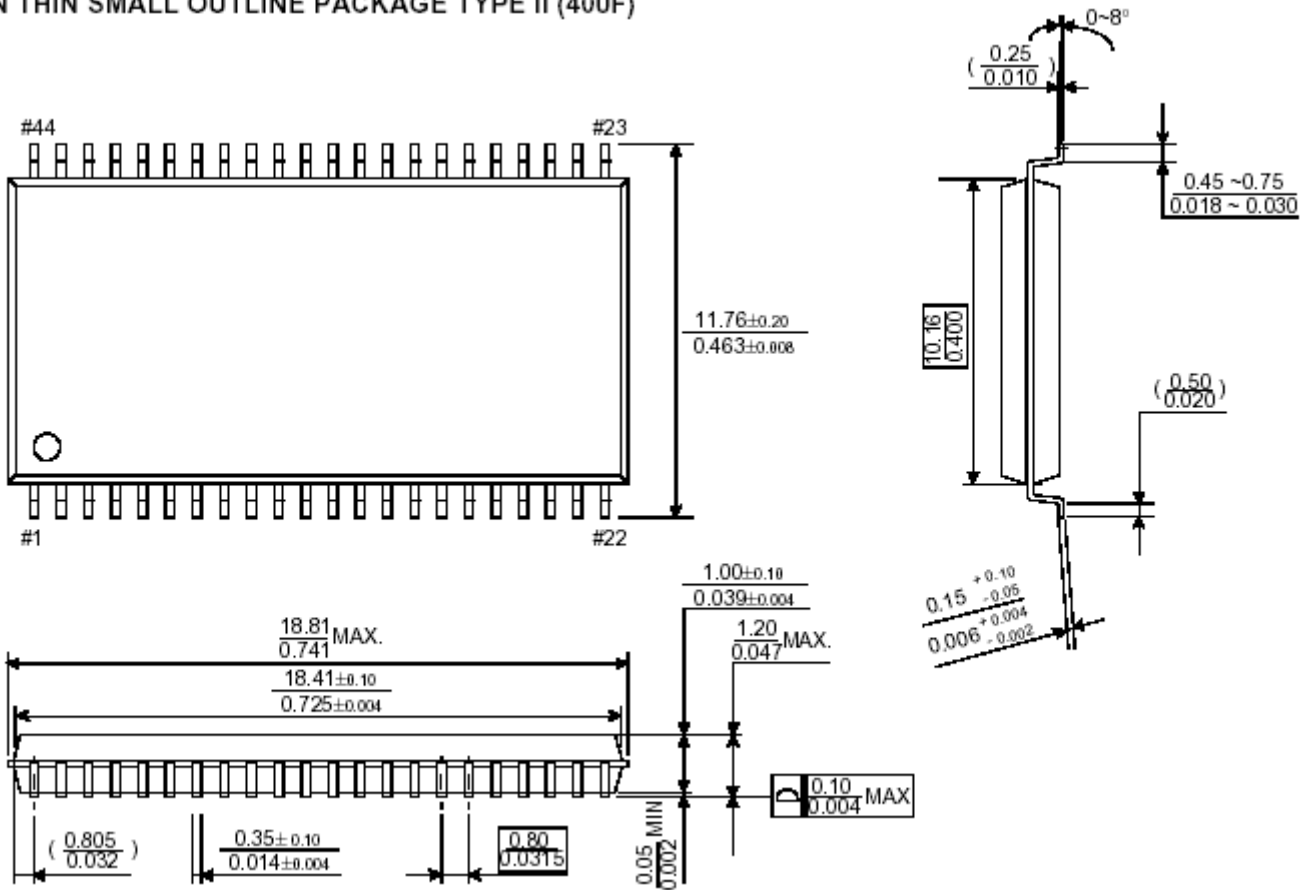
DATA RETENTION WAVE FORM



PACKAGE DIMENSION

44 - TSOP2 (0.8mm pin pitch)

Unit : millimeters / inches

44 PIN THIN SMALL OUTLINE PACKAGE TYPE II (400F)


ORDERING INFORMATION

Alliance Part no	Organization	Vcc Range	Package	Operating Temp	Speed ns
AS6C8016A-55ZIN - Tray	512K x 16	2.7V – 3.6V	44 PIN TSOP2 (0.8MM PIN PITCH)	-40°C~85°C	55
AS6C8016A-55ZINTR – Tape & Reel	512K x 16	2.7V – 3.6V	44 PIN TSOP2 (0.8MM PIN PITCH)	-40°C~85°C	55

PART NUMBERING SYSTEM

AS6C	8016	A	-55	Z	I	N
LOW POWER SRAM PREFIX	DEVICE NUMBER 80 = 8M 16 = by 16	Device revision or sub-contract Wafer build supplier identification	Access Time	44 PIN TSOP2 (0.8MM PIN PITCH)	Temperature range: I = Industrial (-40°C to 85°C)	N = Lead Free ROHS Compliant Part